

Title (en)
VERTICALLY INTEGRATED SEMICONDUCTOR SYSTEM

Title (de)
VERTIKAL INTEGRIERTE HALBLEITERANORDNUNG

Title (fr)
ENSEMBLE SEMI-CONDUCTEUR INTEGRE VERTICALEMENT

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Application
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Abstract (en)
[origin: WO0041241A1] The invention relates to a semiconductor system which comprises at least one semiconductor chip having a first and a second main side. Said first and second main sides are provided with active structures that are connected to each other by means of interconnections passing through the semiconductor chip. The at least one semiconductor chip is arranged such that one of its main sides rests on a first main side of a support.

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